Material Declaration Report

Package Type:	TSSOP 8L (4.4mm)
Pericom Package Code:	L8(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	33.000
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	6/4/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
			Silica Fused	60676-86-0	89.800	18.0959
MOLD COMPOUND	20.151	OSE	Epoxy Resin	Proprietary	5.000	1.0076
			Phenolic Resin	Proprietary	4.000	0.8061
			Others	Proprietary	1.000	0.2015
			Carbon Black	1333-86-4	0.200	0.0403
		SPEL and UTL	Silica Fused	60676-86-0	88.000	17.7331
			Epoxy Resin	Proprietary	5.000	1.0076
			Phenolic Resin	Proprietary	4.500	0.9068
			Epoxy, Cresol Novolac	29690-82-2	2.000	0.4030
			Carbon Black	1333-86-4	0.500	0.1008
			Copper	7440-50-8	95.140	10.2303
LEADFRAME	10.753		Nickel	7440-02-0	3.200	0.3441
			Silver	7440-22-4	0.760	0.0817
			Silicon	7440-21-3	0.725	0.0780
			Magnesium	7439-95-4	0.175	0.0188
SILICON DIE	1.031		Silicon (Si)	7440-21-3	99.192	1.0225
			Non-hazardous Metal	Proprietary	0.808	0.0083
			Silver	7440-22-4	76.000	0.2908
DIE ATTACH EPOXY	0.383	OSE	Acrylic Resin	Proprietary	8.000	0.0306
			Acrylate	Proprietary	5.500	0.0210
			Polybutadiene derivative	Proprietary	5.500	0.0210
			Epoxy resin	Proprietary	2.500	0.0096
			Additive	Proprietary	1.000	0.0038
			Butadiene copolymer	Proprietary	1.000	0.0038
			Peroxide	Proprietary	0.500	0.0019
		SPEL	Silver	7440-22-4	80.000	0.3061
			Epoxy Resin	9003-36-5	10.000	0.0383
			Diluent	26447-14-3	6.000	0.0230
			Hardener	620-92-8	3.250	0.0124
			Dicyandamide	461-58-5	0.750	0.0029
		UTL	Silver	7440-22-4	80.000	0.3061
			Functionalized Urethane	72869-86-4	8.000	0.0306
			Diester Resin	94-80-4	7.000	0.0268
			Epoxy Resin	Proprietary	5.000	0.0191
GOLD WIRE	0.062		Gold(Au)	7440-57-5	99.990	0.0620
			Impurities	-	0.010	0.0000
SOLDER PLATING	0.620		Tin (Sn)	7440-31-5	99.990	0.6203
			Impurities	-	0.010	0.0001

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
Device	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb	Hg	Cr+6	Cd	PBB	PBDE
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.